

LH5324C00

24M-bit Mask-Programmable ROM

■ Description

The LH5324C00D (User's No. : LH536CXX) is a CMOS 24M-bit mask-programmable ROM organized as 1 572 864 × 16 bits. It is fabricated using silicon-gate CMOS process technology.

■ Features

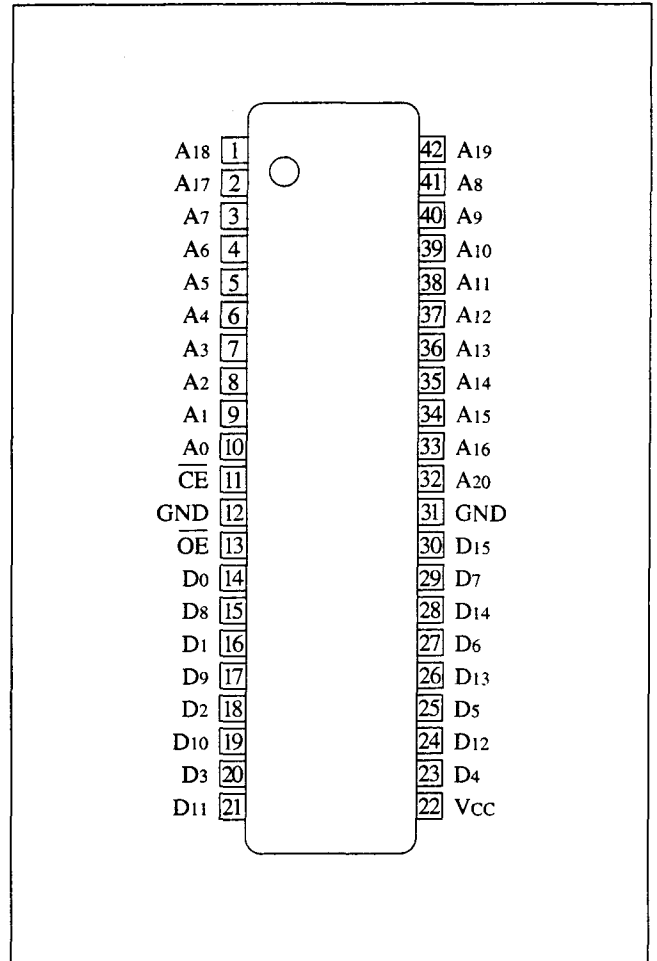
1. 1 572 864 × 16 bit organization
2. Maximum access time 120 ns
3. Maximum supply current
 - Operating 80 mA
 - Standby 100 μA
4. Static operation (Internal sync. system)
5. TTL compatible I/O
6. Three-state outputs
7. Supply voltage 5 V ± 10%
8. Package
 - 42-pin DIP (DIP042-P-0600)

■ Pin Description

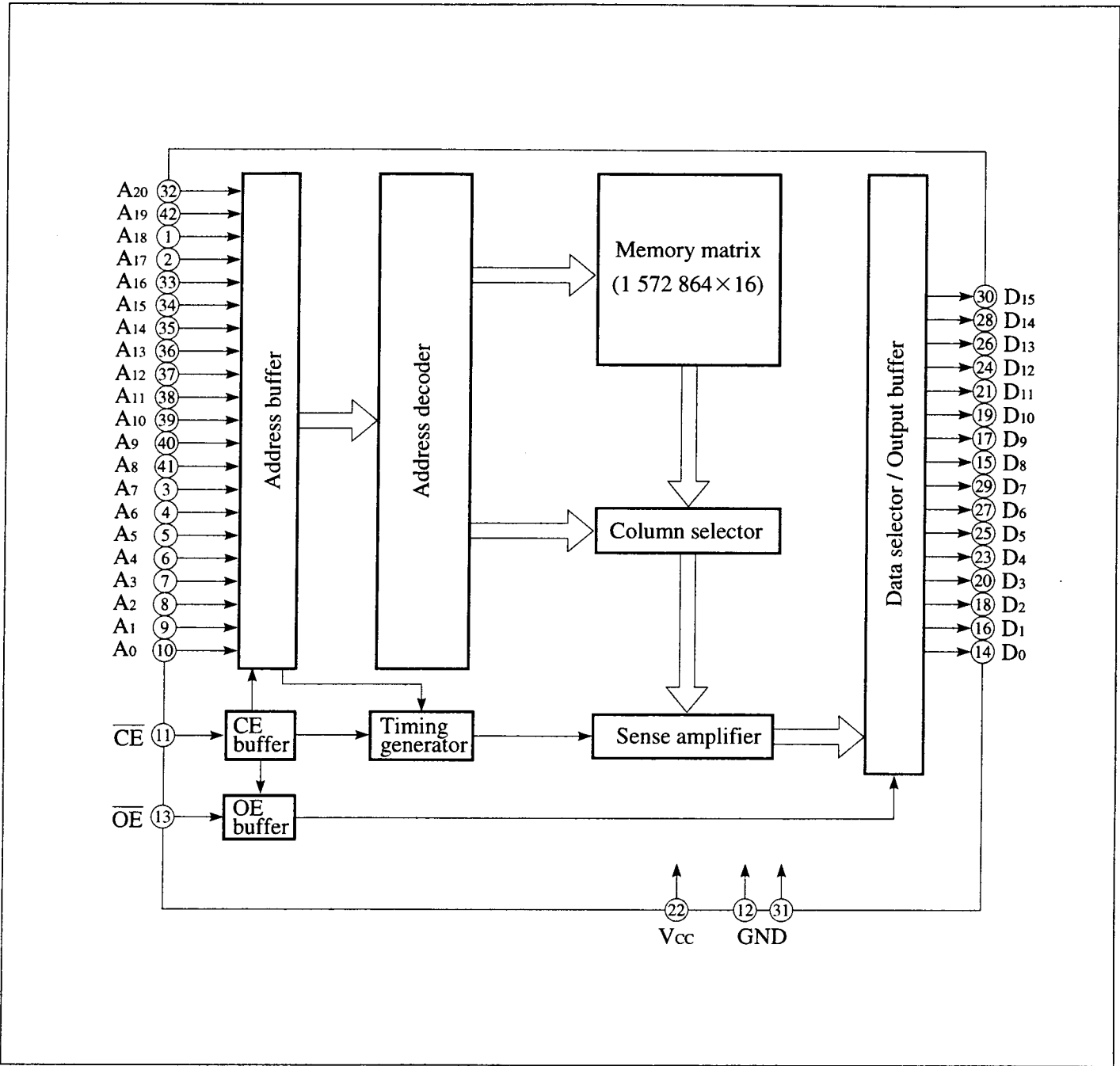
Signal	Pin name	Note
A ₀ -A ₂₀	Address input	1
D ₀ -D ₁₅	Data output	
$\overline{\text{CE}}$	Chip enable input	
$\overline{\text{OE}}$	Output enable input	
V _{CC}	Power supply	
GND	Ground	

Note 1. When the address input at both A₁₉ and A₂₀ is high level, the data outputs become high impedance. Because this address area does not have data.

■ Pin Connections



■ Block Diagram



■ Truth Table

\overline{CE}	\overline{OE}	A ₀ -A ₁₈	A ₁₉	A ₂₀	Data output	Supply current
High	X	X	X	X	High impedance	Standby
Low	High	X	X	X	High impedance	Operating
Low	Low	X	Low	Low	Output	Operating
Low	Low	X	Low	High	Output	Operating
Low	Low	X	High	Low	Output	Operating
Low	Low	X	High	High	High impedance	Operating

X : Don't Care

■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.3 to +7.0	V
Input voltage	V _{IN}	-0.3 to V _{CC} +0.3	V
Output voltage	V _{OUT}	-0.3 to V _{CC} +0.3	V
Operating temperature	T _{opr}	0 to 70	°C
Storage temperature	T _{stg}	-65 to +150	°C

■ Recommended Operating Conditions

(T_a=0 to 70 °C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}	4.5	5.0	5.5	V

DC Characteristics

($V_{CC}=5\text{ V}\pm 10\%$ 、 $T_a=0\text{ to }70\text{ }^\circ\text{C}$)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit	Note
Input "High" voltage	V_{IH}		2.2		$V_{CC}+0.3$	V	
Input "Low" voltage	V_{IL}		-0.3		0.8	V	
Output "High" voltage	V_{OH}	$I_{OH} = -400\ \mu\text{A}$	2.4			V	
Output "Low" voltage	V_{OL}	$I_{OL} = 2.0\ \text{mA}$			0.4	V	
Input leakage current	$ I_{LI} $	$V_{IN}=0\ \text{V}, V_{CC}$			10	μA	
Output leakage current	$ I_{LO} $	$V_{OUT}=0\ \text{V}, V_{CC}$			10	μA	2
Supply current (Operating)	I_{CC1}	$t_{RC} = 120\ \text{ns}$			80	mA	
	I_{CC2}	$t_{RC} = 1.0\ \mu\text{s}$			70	mA	3
Supply current (Standby)	I_{SB1}	$\overline{CE} = V_{IH}$			2.0	mA	
	I_{SB2}	$\overline{CE} = V_{CC} - 0.2\ \text{V}$			100	μA	
Input capacitance	C_{IN}	$f = 1.0\ \text{MHz}, T_a = 25\text{ }^\circ\text{C}$			10	pF	
Output capacitance	C_{OUT}				10	pF	

Note 2. $\overline{CE} = V_{IH}, \overline{OE} = V_{IH}$

Note 3. $V_{IN} = V_{IH}/V_{IL}, \overline{CE} = V_{IL}$ (Output is open)

AC Characteristics

($V_{CC}=5\text{ V}\pm 10\%$ 、 $T_a=0\text{ to }70\text{ }^\circ\text{C}$)

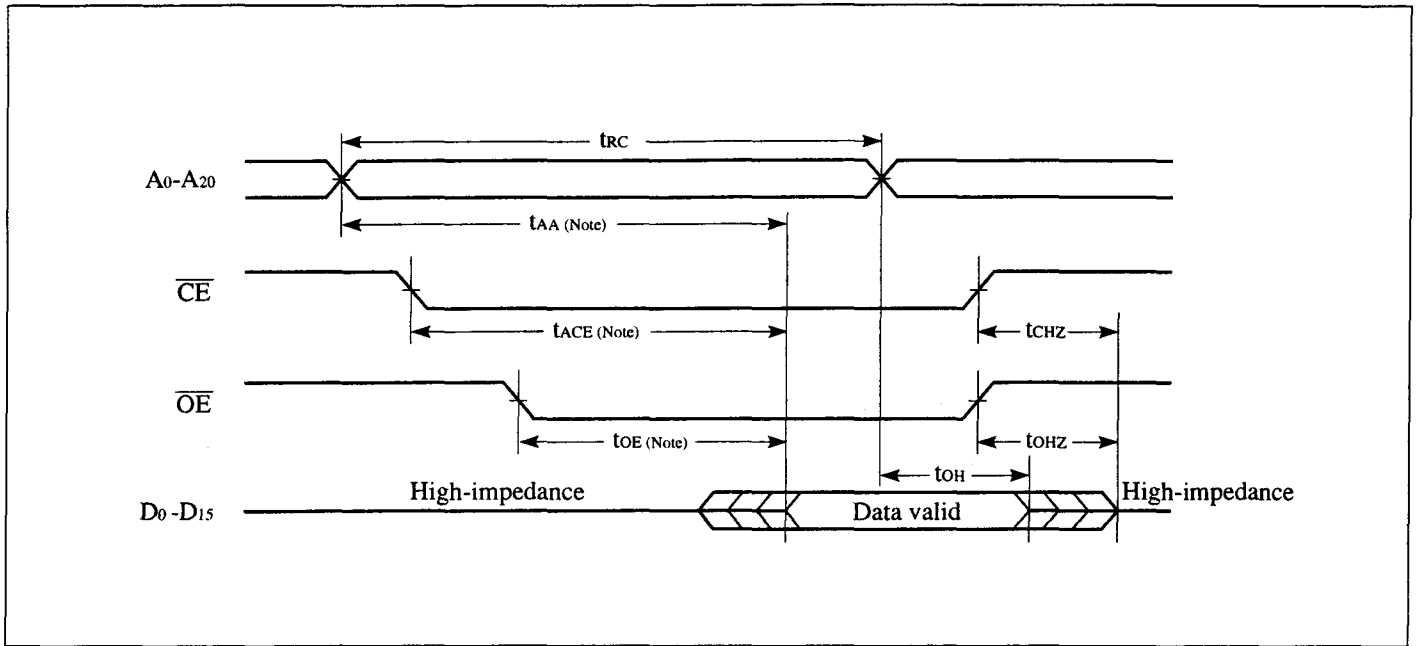
Parameter	Symbol	MIN.	TYP.	MAX.	Unit	Note
Read cycle time	t_{RC}	120			ns	
Address access time	t_{AA}			120		
Chip enable access time	t_{ACE}			120		
Output enable delay time	t_{OE}			60		
Output hold time	t_{OH}	0				
Output floating time	t_{CHZ}			50	4	
	t_{OHZ}			50		
	t_{AHZ}			60		

Note 4. Determined by the time for the output to be opened. (Irrespective of output voltage)

AC Test Conditions

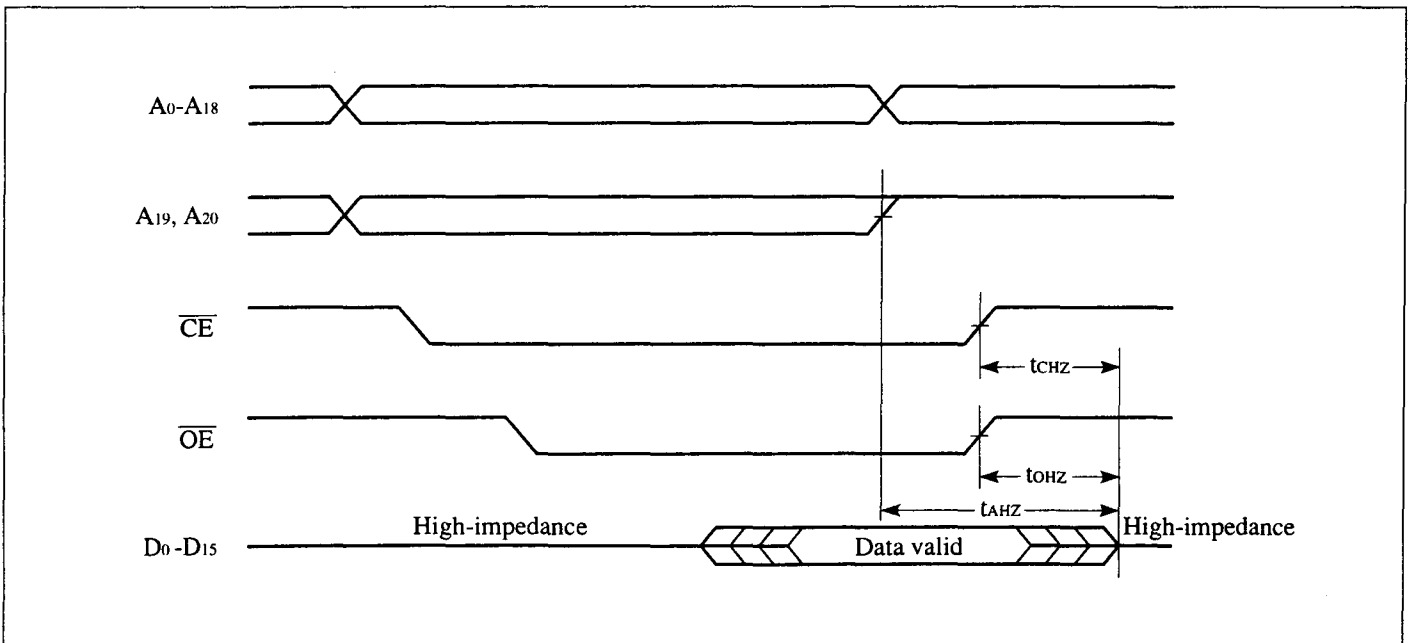
- Input voltage amplitude : 0.6 to 2.4 V
- Input signal rise / fall time : 10 ns
- Input reference level : 1.5 V
- Output reference level : 1.5 V
- Output load condition : 1TTL + 100 pF

■ Timing Diagram



Note The output data becomes valid when the last interval t_{AA} , t_{ACE} or t_{OE} have concluded.

〈When the address input at both A₁₉ and A₂₀ high level〉



Sharp's Product Line-up (24M-bit Mask ROM)

★Under development

Configuration (words×bits)	Pinout*	Model No.	User's No.	Access time (ns) MAX. Cycle time (ns) MIN.	Supply current (mA) MAX.	Supply voltage (V)	Package
3M×8	M	LH5324000D	LH5360XX	150	70	5±10%	42DIP
1.5M×16	M	LH5324C00D	LH536CXX	120	80	5±10%	42DIP
1.5M×16	M	LH5324A00AD	LH536GXX	150	65	5±10%	42DIP
3M×8 1.5M×16	M	LH5324P00N	LH536PXX	120	80	5±10%	44SOP
3M×8 1.5M×16	M	★LH5324P00T/TR	LH536DXX	120	80	5±10%	48TSOP(I) forward bend/ 48TSOP(I) reverse bend
3M×8 1.5M×16	M	LH5324500N	LH5365XX	150	70	5±10%	44SOP

* M : Mask ROM specific pinout